

# Chip Scale Review®

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The Future of Semiconductor Packaging

## 2016 Editorial Calendar

### July • August

Materials development of SiP & IoT	<ul style="list-style-type: none"><li>• <b>ICEPT 2016</b> Wuhan, China (Aug 16-19)</li><li>• <b>SEMICON Taiwan</b> Taipei, Taiwan (Sept 7-9)</li><li>• <b>BiTS China 2016</b> Suzhou, China (Sept 13)</li><li>• <b>ESTC</b> Grenoble, France (Sept 13-16)</li><li>• <b>MEPTEC</b> <b>Medical Electronics Symposium</b> Portland, OR (Sept 14-16)</li><li>• <b>SEMI European MEMS Summit</b> Stuttgart, Germany (Sept 15-16)</li></ul>
Silicon 3D Integration for small power devices	
Solder reliability	
Environmental impact of packaging processes	
MEMS challenges in the IoT era	
Materials for test sockets	
Direct bonding technology	
Warpage in FCBGAs	
<b>International Directory of Bonding Equipment for 2.5D and 3D Assembly</b>	
<b>Ad Space Close Jun 24 - Ad Materials Close Jul 1</b>	

### September • October

Panel Level Packaging for FO-WLP	<ul style="list-style-type: none"><li>• <b>IMAPS 2016</b> Pasadena, CA (Oct 11-13)</li><li>• <b>ICPT 2016</b> Beijing, China (Oct 17-19)</li><li>• <b>IWLPC-International Wafer-Level Packaging Conference &amp; Exhibition</b> San Jose, CA (Oct 18-20)</li><li>• <b>SEMICON Europa</b> Grenoble, France (Oct 25-27)</li></ul>
Probe card inspection	
Trends in TSV technologies	
Market update on multi-die ICs	
Bonding / debonding for heterogeneous integration	
Hermetic CSP for MEMS	
LED packaging	
Micro testing thin die	
SiP	
Ad Space Close Sep 9 - Ad Materials Close Sep 16	

### November • December

FOWLP in the foundry	<ul style="list-style-type: none"><li>• <b>MEMS Executive Congress</b> Scottsdale, AZ (Nov 10-11)</li><li>• <b>MEPTEC Semiconductor Packaging Roadmap Symposium</b> San Jose, CA (Nov 14)</li><li>• <b>International Test Conference (ITC)</b> Fort Worth, TX (Nov 15-17)</li><li>• <b>SEMICON Japan</b> Tokyo, Japan (Dec 14-16)</li><li>• <b>3D ASIP Conference</b> Redwood City, CA (Dec 15-17)</li></ul>
3D TSV assembly	
Die stacking	
High-frequency test sockets	
Wafer-level test	
High performance photoresist for advanced packaging	
Dicing of silicon carbide power devices	
Glass for semiconductor/optoelectronics packaging	
Interconnects for MEMS & sensors	

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